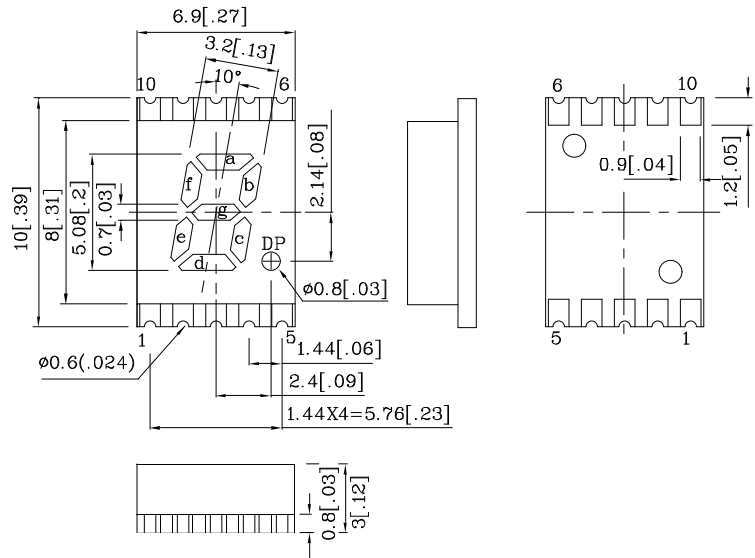
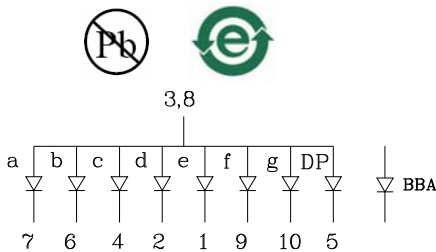


PRELIMINARY SPEC

Features

- 0.21 INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- I.C. COMPATIBLE.
- MECHANICALLY RUGGED.
- GRAY FACE, WHITE SEGMENT.
- PACKAGE : 650 PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ " unless otherwise noted.
3. The gap between the reflector and PCB shall not exceed 0.25mm.
4. Specifications are subject to change without notice.

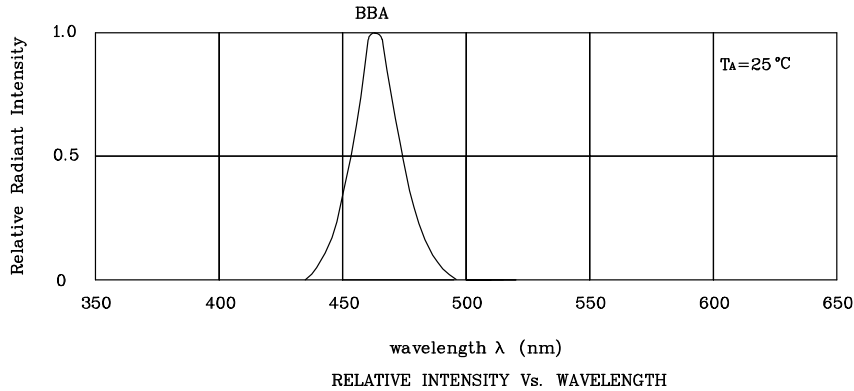


ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE

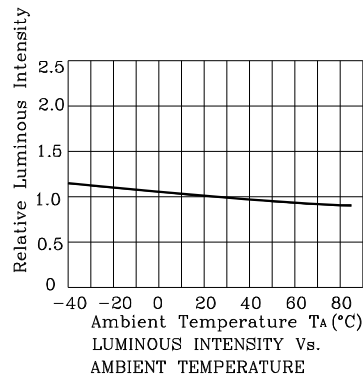
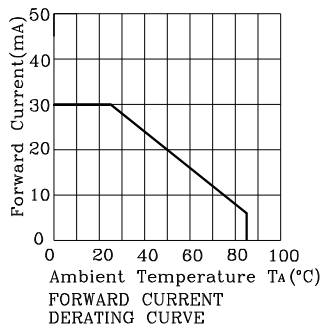
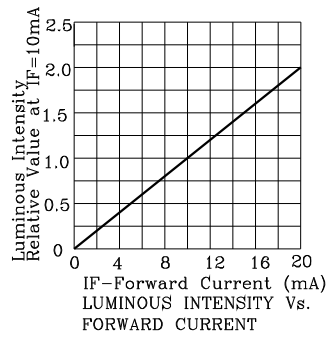
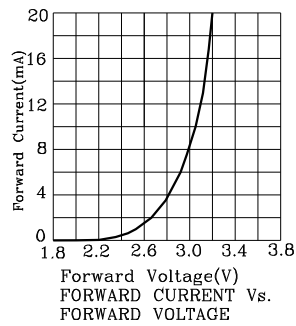
Absolute Maximum Ratings (TA=25°C)		BBA (InGaN)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	100	mA
Power Dissipation	P _T	120	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	
Electrostatic Discharge Threshold (HBM)		1000	V

Operating Characteristics (TA=25°C)		BBA (InGaN)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V _F	3.05	V
Forward Voltage (Max.) (I _F =10mA)	V _F	4.0	V
Reverse Current (Max.) (V _R =5V)	I _R	10	uA
Wavelength of Peak Emission (Typ.) (I _F =10mA)	λ _P	468	nm
Wavelength of Dominant Emission (Typ.) (I _F =10mA)	λ _D	470	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	Δλ	21	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	100	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity (I _F =10mA) ucd		Wavelength nm λ _P	Description
			min.	typ.		
ZFBBA05A	Blue	InGaN	1200	4990	468	Common Anode. Rt. Hand Decimal



❖ BBA



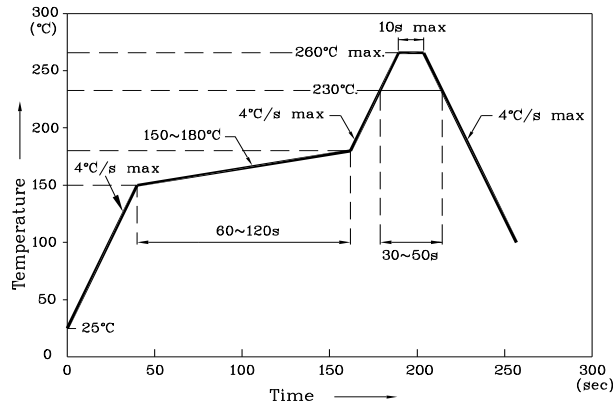
Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

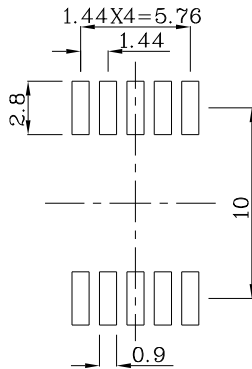
Reflow Soldering Profile For Lead-free SMT Process.



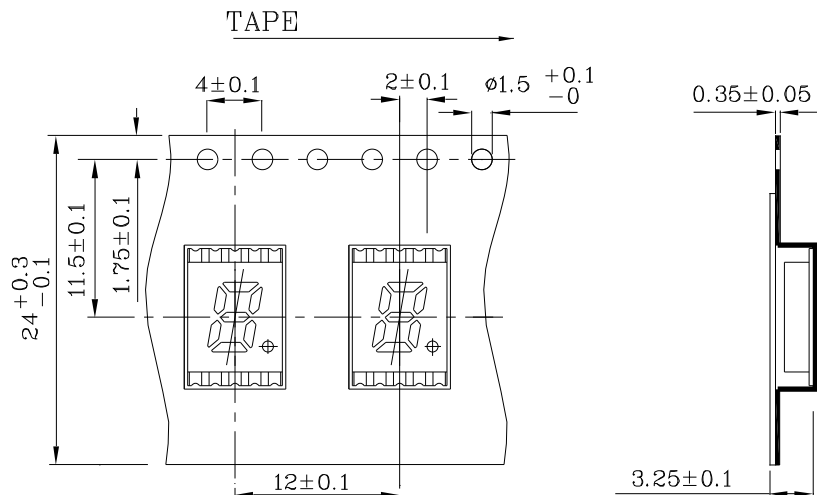
Notes:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C~260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern (Units : mm;Tolerance: ± 0.15)



❖ Tape Specification (Units : mm)



PACKING & LABEL SPECIFICATIONS

ZFBBA05A

